#### 507593105 11/10/2022

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7639995

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
WEIMIN DUAN	04/23/2021
ALEXANDROS MANOLAKOS	04/23/2021
HUNG DINH LY	04/26/2021

## **RECEIVING PARTY DATA**

Name:	QUALCOMM INCORPORATED	
Street Address:	5775 MOREHOUSE DRIVE	
City:	SAN DIEGO	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	18054417	

## CORRESPONDENCE DATA

Fax Number: (619)235-0398

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 619-238-1900

Email: Docketing@procopio.com, Patrick.Lemus@procopio.com

PROCOPIO CORY HARGREAVES & SAVITCH LLP **Correspondent Name:** 

Address Line 1: 525 B STREET, SUITE 2200

Address Line 4: SAN DIEGO, CALIFORNIA 92101

ATTORNEY DOCKET NUMBER:	129025-1674CT01/2100622C1	
NAME OF SUBMITTER:	PATRICK LEMUS	
SIGNATURE:	/Patrick Lemus/	
DATE SIGNED:	11/10/2022	

## **Total Attachments: 4**

source=2100622C1\_Assignment\_FromParent#page1.tif source=2100622C1\_Assignment\_FromParent#page2.tif source=2100622C1\_Assignment\_FromParent#page3.tif source=2100622C1 Assignment FromParent#page4.tif

## **ASSIGNMENT**

WHEREAS, WE,

- 1. Weimin DUAN, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121,
- 2. Alexandros MANOLAKOS, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121,
- 3. Hung Dinh LY, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **GEOMETRIC DILUTION OF PRECISION BASED TRANSMIT/RECEIVE POINT SELECTION FOR WIRELESS POSITIONING** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 17/218,418 filed March 31, 2021, Qualcomm Reference Number 2100622, and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world

in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance:

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Scar Diego, CA, CA, On 04/23/2021

City, State, Country Date

REEL: 061726 FRAME: 0270

**PATENT** 

Qualcomm Reference Number: 2100622

Page 3 of 3

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Erondido, Aust 4/23/2021

lexandros MANOLAKOS

Done at \_\_\_\_\_\_, on \_\_\_\_\_

City, State, Country Date Hung Dinh LY

PATENT Qualcomo Reference Number 2180622 (1995 3 of )

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at on		
City, State, Country	Date	Alexandros MANOLAKOS
Done as Save Niggo 14, on O4!	16/2021	/UV
City, Same, Channey	Duc	Hung Diah LY

**RECORDED: 11/10/2022**